Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

Vishay Semiconductor/Opto Division
VSMY1850X01

For any questions, you can email us directly:
sales@integrated-circuit.com

High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology

21531

FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- Peak wavelength: λ_p = 850 Nm
- High reliability
- High radiant power
- High radiant intensity
- High speed
- Angle of half sensitivity: ϑ = ± 60°
- Suitable for high pulse current operation
- 0805 standard surface-mountable package
- Floor life: 168 h, MSL 3, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE

Pb-free

e4

RoHS COMPLIANT

HALOGEN FREE

GREEN (5-2008)

DESCRIPTION

As part of the SurfLight™ portfolio, the VSMY1850X01 is an infrared, 850 nm emitting diode based on GaAlAs surface emitter chip technology with high radiant intensity, high optical power and high speed, molded in clear, untinted 0805 plastic package for surface mounting (SMD).

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR touch panels
- IR flash
- IR illumination
- 3D TV

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr)	φ (deg)	λ_p (nm)	t_r (ns)
VSMY1850X01	10	± 60	850	10

Note

- Test conditions see table “Basic Characteristics“

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY1850X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	t_p/T = 0.5, t_p = 100 µs	I_{FM}	200	mA
Surge forward current	t_p = 100 µs	I_{FSM}	1	A
Power dissipation		P_V	190	mW
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	-40 to +85	°C
Storage temperature range		T_{stg}	-40 to +100	°C
Soldering temperature	According to Fig. 7, J-STD-020	T_{sd}	260	°C
Thermal resistance junction / ambient	JESD 51	R_{thJA}	270	K/W

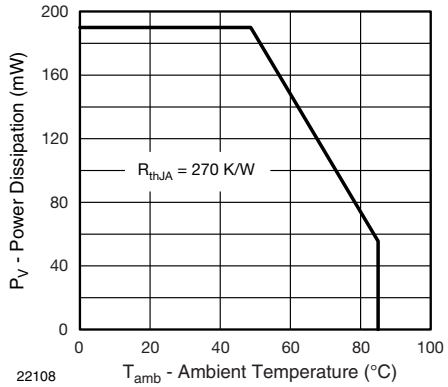


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

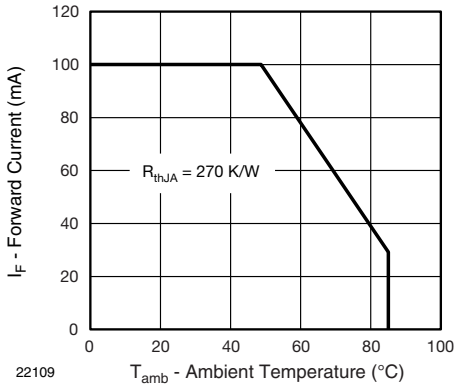


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 100 mA, t_p = 20 ms	V_F	-	1.65	1.9	V
	I_F = 1 A, t_p = 100 µs	V_F	-	2.9	-	V
Temperature coefficient of V_F	I_F = 1 mA	TK_{VF}	-	-1.4	-	mV/K
	I_F = 10 mA	TK_{VF}	-	-1.18	-	mV/K
Reverse current		I_R	Not designed for reverse operation			µA
Junction capacitance	V_R = 0 V, f = 1 MHz, E = 0 mW/cm²	C_J	-	125	-	pF
Radiant intensity	I_F = 100 mA, t_p = 20 ms	I_e	5	10	15	mW/sr
	I_F = 1 A, t_p = 100 µs	I_e	-	85	-	mW/sr
Radiant power	I_F = 100 mA, t_p = 20 ms	ϕe	-	50	-	mW
Temperature coefficient of radiant power	I_F = 100 mA	$TK\phi_e$	-	-0.35	-	%/K
Angle of half intensity		φ	-	± 60	-	deg
Peak wavelength	I_F = 100 mA	λ_p	840	850	870	nm
Spectral bandwidth	I_F = 30 mA	$\Delta\lambda$	-	30	-	nm
Temperature coefficient of λ_p	I_F = 30 mA	$TK_{\lambda p}$	-	0.25	-	nm/K
Rise time	I_F = 100 mA, 20 % to 80 %	t_r	-	10	-	ns
Fall time	I_F = 100 mA, 20 % to 80 %	t_f	-	10	-	ns
Virtual source diameter		d	-	0.5	-	mm

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

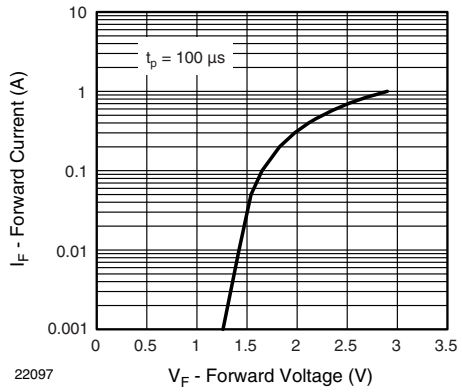


Fig. 3 - Forward Current vs. Forward Voltage

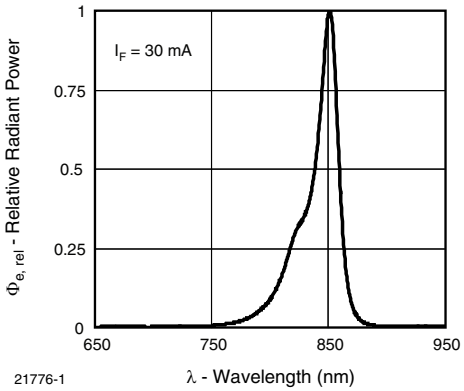


Fig. 5 - Relative Radiant Power vs. Wavelength

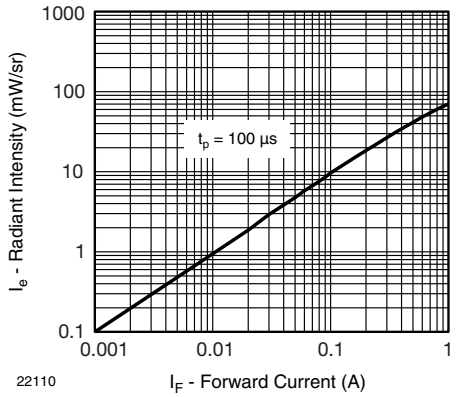


Fig. 4 - Radiant Intensity vs. Forward Current

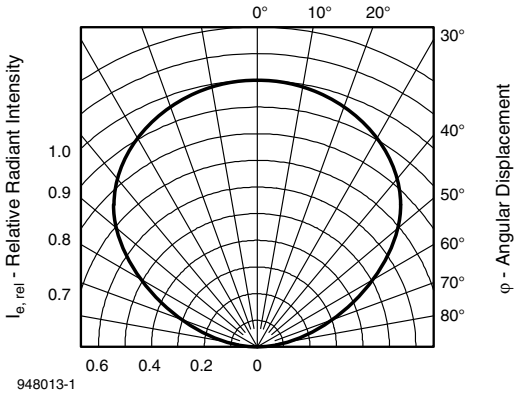


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

REFLOW SOLDER PROFILE

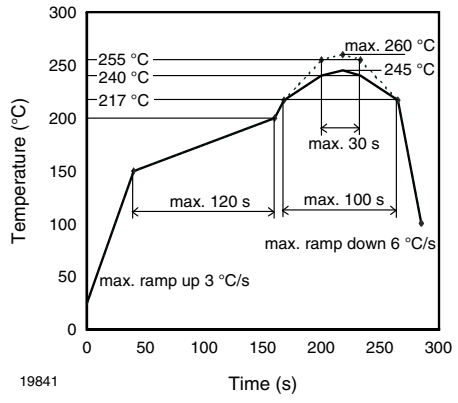


Fig. 7 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

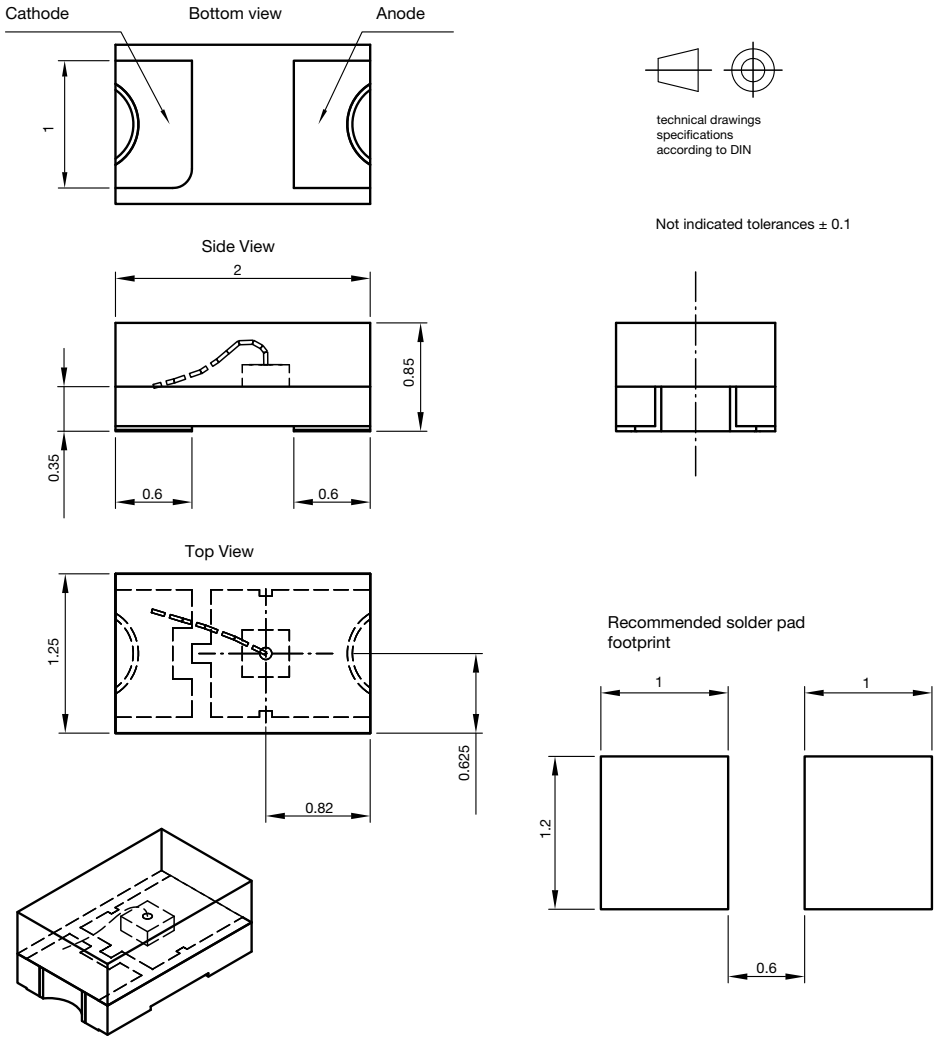
FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:
Moisture sensitivity: level 3
Floor life: 168 h
Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

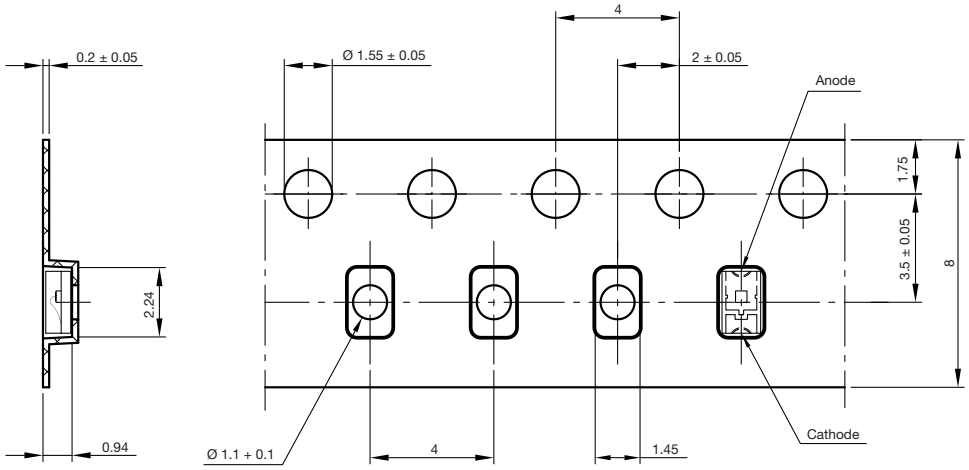
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.541-5083.01-4
Issue: 2; 10.09.2013

BLISTER TAPE DIMENSIONS in millimeters



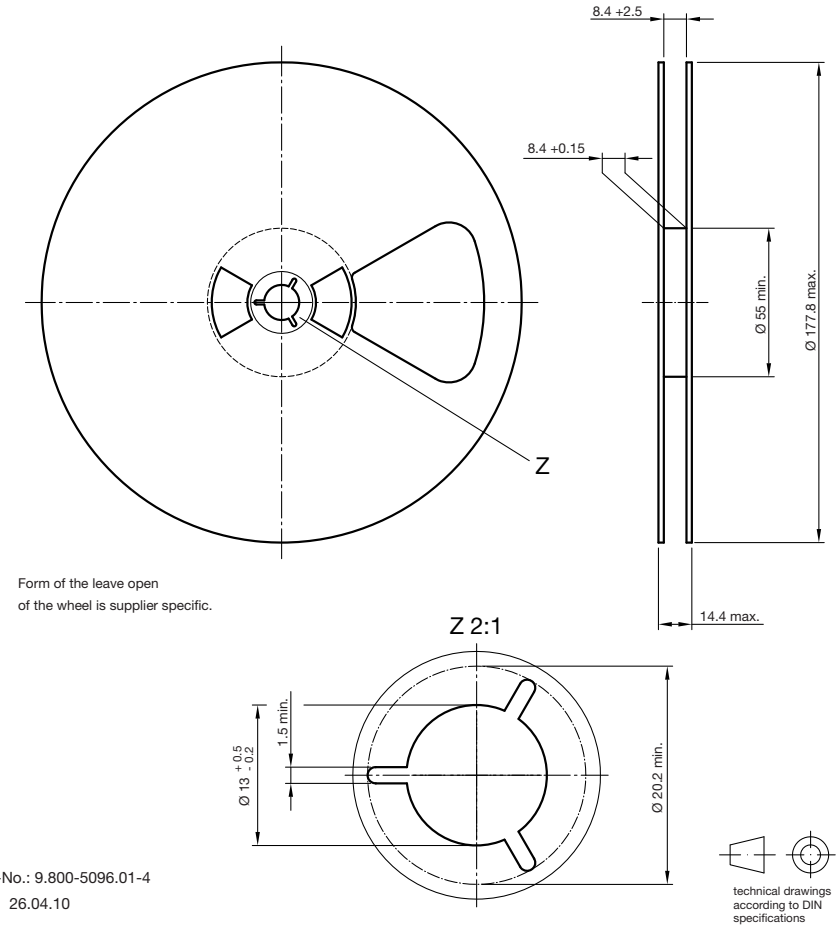
Not indicated tolerances ±0.1

Reel off direction

Drawing-No.: 9.700-5352.01-4
Issue: 1; 13.04.10
22112

technical drawings
according to DIN
specifications

REEL DIMENSIONS in millimeters



Form of the leave open
of the wheel is supplier specific.

Drawing-No.: 9.800-5096.01-4
Issue: 2; 26.04.10
20875

technical drawings
according to DIN
specifications

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